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電源管理



顯示驅動



二三極管



LDO穩壓器



觸摸芯片



MOS管



運算放大器



存儲芯片



MCU



串口通信

A04409-TD

產品規格說明書

General Description:

The AO4409-TD is the single P-Channel logic enhancement mode power field effect transistors to provide excellent RDS(on), low gate charge and low gate resistance. It's up to -30V operation voltage is well suited in switching mode power supply, SMPS, notebook computer power management and other battery powered circuits.

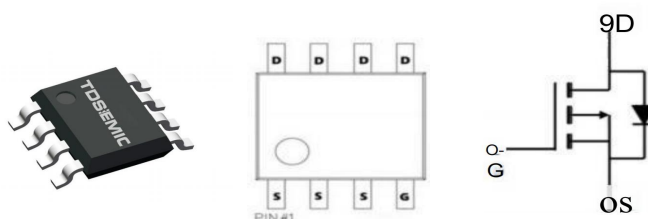
Applications

Switching power supply, SMPS
Battery Powered System
DC/DC Converter
DC/AC Converter
Load Switch

Features:

RDS(ON) < 7.5m @ VGS = 10V (P-Ch)
RDS(ON) < 13 m @ VGS = 4.5V (P-Ch)
Super high density cell design for extremely low
RDS(ON) Exceptional on-resistance and maximum DC current

SOP-8 Pin Configuration



Package Marking and Ordering Information

Product ID	Package	Marking	QTY (PCS)	Packing method
A04409-TD	SOP-8	A04409-TD	3000	Reel

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{DS} @-10V1.6	-18	A
I _D @T _C =100°C	Continuous Drain Current, V _{DS} @-10V1.6	-8.8	A
I _{DM}	Pulsed Drain Current ²	-53	A
E _{AS}	Single Pulse Avalanche Energy ³	-80	mJ
I _{AS}	Avalanche Current	-40	A
P _o @T _C =25°C	Total Power Dissipation ⁴	90	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C
R _{θJA}	Thermal Resistance Junction-ambient ¹ (t ≤ 10S)	20	°C/W
	Thermal Resistance Junction-ambient ¹ (Steady State)	50	°C/W

ReJC	Thermal Resistance Junction-case 1	1.6	°C/W
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Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{oss}	Drain-Source Breakdown Voltage	V _{gs} =0V, I _p =-250uA	-30	-----	---	V
RDS(ON)	Static Drain-Source On-Resistance ²	V _{gs} =-10V, I _p =-20A	---	5.6	7.5	mΩ
		V _{gs} =-4.5V, I _b =-15A	---	9.5	13	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{cs} =V _{os} , I _o =-250uA	-1.2	---	-2.5	V
I _{oss}	Drain-Source Leakage Current	V _{os} =-24V, V _{ss} =0V, T _J =25°C	---	-----	-1	uA
		V _{os} =-24V, V _{gs} =0V, T _J =55°C	---	---	-5	
I _{css}	Gate-Source Leakage Current ^{tt}	V _{gs} =±20V, V _{os} =0V	---	-----	±100	nA
R _g	Gate Resistance	V _{os} =0V, V _{gs} =0V, f=1MHz	---	1.2	---	Ω
Q _g	Total Gate Charge(-10V)	V _{os} =-15V, V _{ss} =-10V, I _b =-18A	---	60	---	nC
Q _{gs}	Gate-Source Charge		---	9	---	
Q _{gd}	Gate-Drain Charge		---	15	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-15V, V _{gs} =-10V R _G =3.3Ω, I _b =-20A	---	17	-----	ns
T _r	Rise Time		---	40	---	
T _{d(of)}	Turn-Off Delay Time		---	55	---	
T _t	FallTime		---	13	---	
C _{iss}	Input Capacitance	V _{os} =-25V, V _{gs} =0V, f=1MHz	---	3450	---	pF
C _{oss}	Output Capacitance		---	255	---	
C _{rss}	Reverse Transfer Capacitance		---	140	---	
I _s	Continuous Source Current ^{1.5}	V _g =V _p =0V, Force Current	---	-----	-70	A
V _{sD}	Diode Forward Voltage ²	V _{gs} =0V, I _s =-1A, T _j =25°C	---	-----	-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-20A, di/dt=100A/us, T _J =25°C	---	22	---	nS
Q _m	Reverse Recovery Charge	T _J =25°C	---	72	---	nC

Note:

1.The data tested by surface mounted on a 1 inch*FR-4 board with 2OZ copper.

2.The data tested by pulsed,pulse width≤300us,duty cycle≤2%

3.The EAS data shows Max.rating.The test condition is V_{oD}=-50V,V_{gs}=-10V,L=0.1mH,I_{As}=-40A

4.The power dissipation is limited by 150°C junction temperature

5.The data is theoretically the same as I_o and I_{om},in real applications,should be limited by total power dissipation

6.The maximum current rating is package limited.

Typical Characteristics

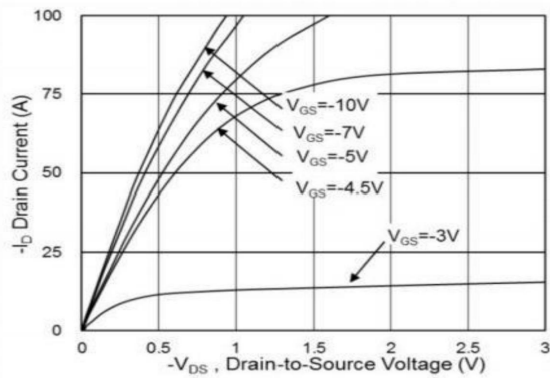


Fig.1 Typical Output Characteristics

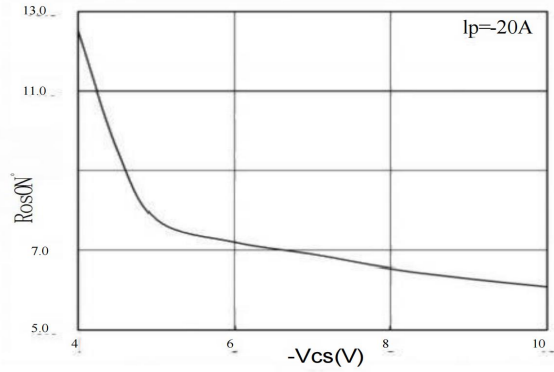


Fig.2 On-Resistance vs. Gate-Source Voltage

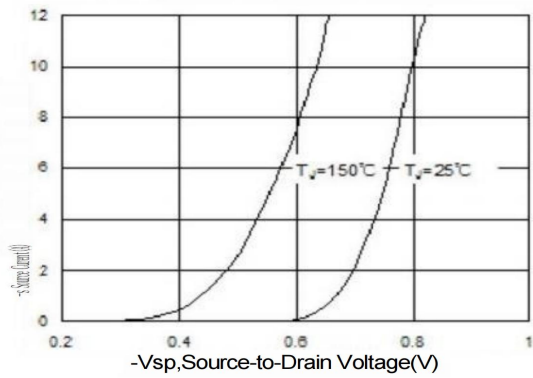


Fig.3 Forward Characteristics of Reverse

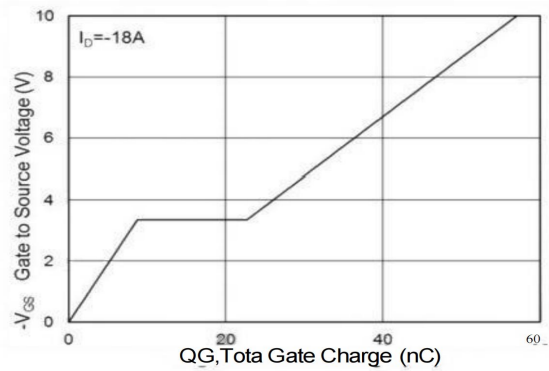


Fig.4 Gate-Charge Characteristics

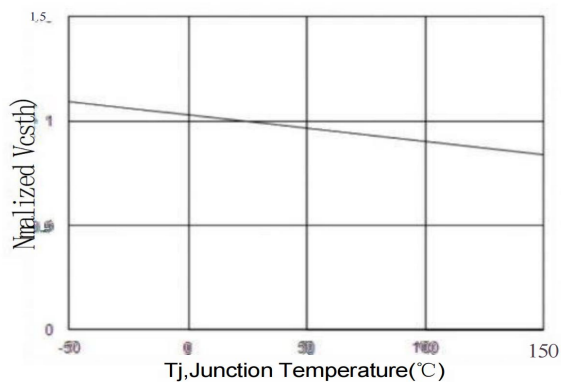


Fig.5 Normalized- $V_{GS(th)}$ vs. T_J

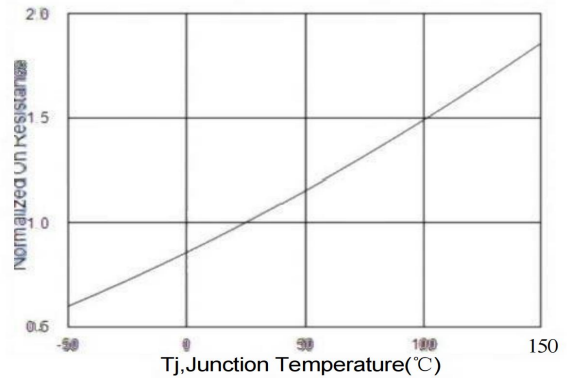


Fig.6 Normalized R_{osON} vs. T_J

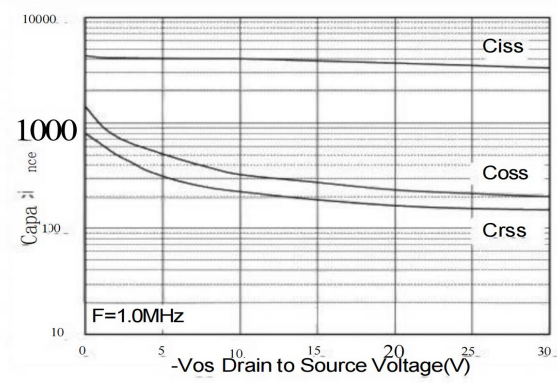


Fig.7 Capacitance

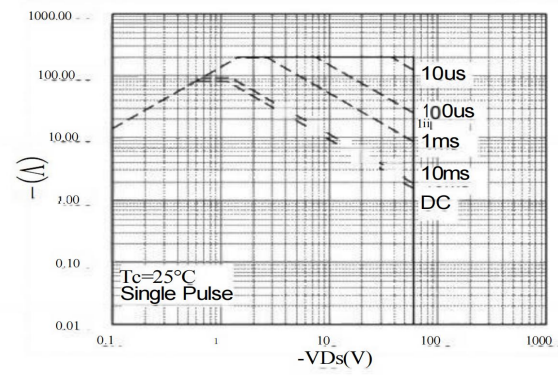


Fig.8 Safe Operating Area

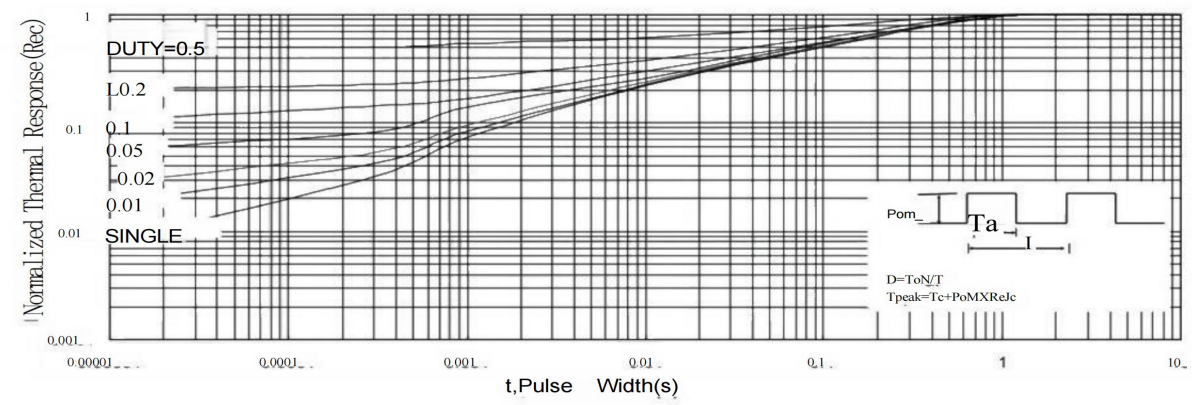


Fig.9 Normalized Maximum Transient Thermal Impedance

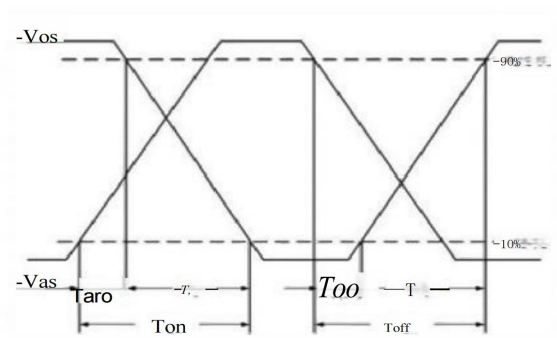


Fig.10 Switching Time Waveform

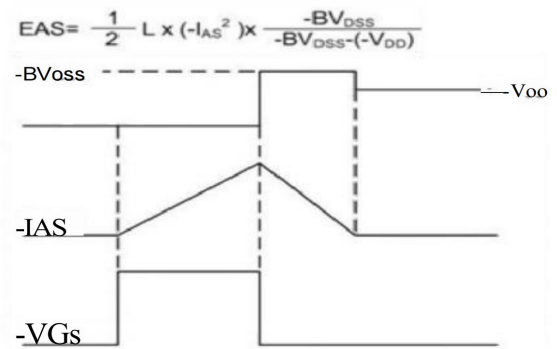
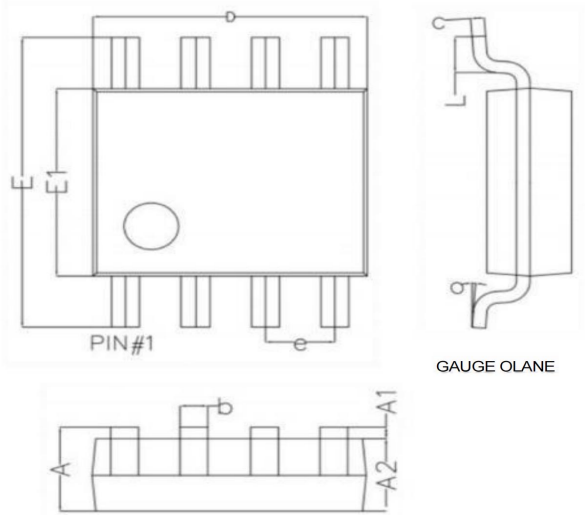


Fig.11 Unclamped Inductive Switching Waveform

SOP8 Package outline



Symbol	Dim in mm		
	Min	Nor	Max
A	1.350	1.550	1.750
A1	0.100	0.175	0.250
A2	1.350	1.450	1.550
b	0.330	0.420	0.510
c	0.170	0.210	0.250
D	4.800	4.900	5.000
e	1.270 (BSC)		
E	5.800	6.000	6.200
E1	3.800	3.900	4.000
L	0.400	0.835	1.2700
0	0°	4°	8°